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FOR REFERENCE ONLY

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-14098	RELEASE FOR RoHS	06/14/2014	Arron Lin
BX1	EDSR#5399	ADD W/O BOARDLOCK OPTION	02/10/2015	Arron Lin

NOTE:

1.MATERIAL

INSULATOR: HIGH TEMP. THERMOPLASTIC, OPTIONS, UL 94V-0, COLOR OPTIONS

CONTACT MATERIAL: HIGH PERFORMANCE COPPER ALLOY.

BOARDLOCK: COPPER ALLOY.

2.FINISH:

CONTACT: SELECTIVE PLATING. ;

SOLDERING AREA: MATTE TIN 100u" MIN. OR GOLD PLATING;

UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN.OVERALL.

BOARDLOCK:

MATTE TIN 100u" MIN. PLATING;

UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN.OVERALL.

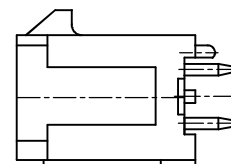
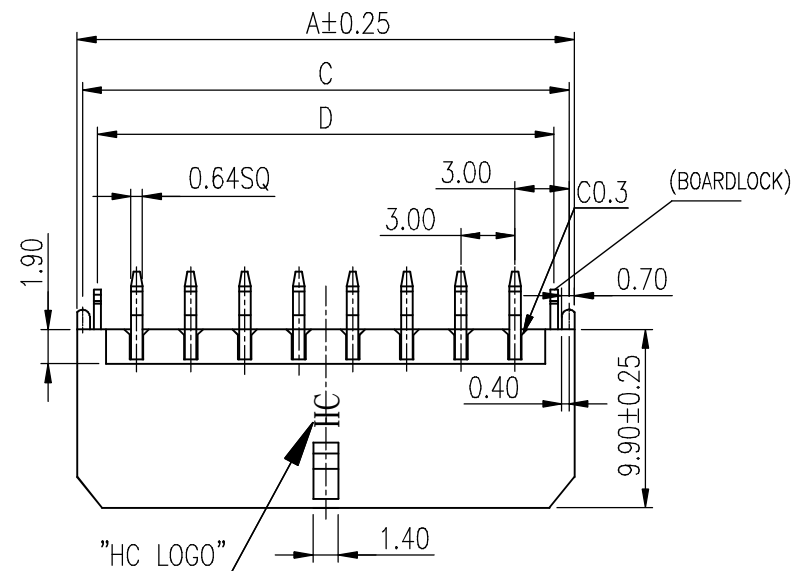
4.THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS

MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.

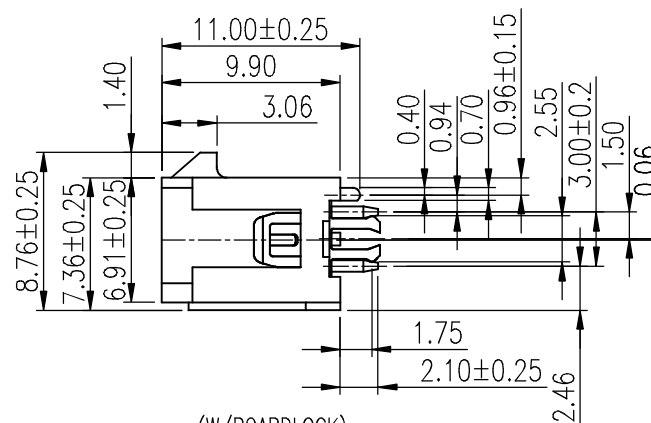
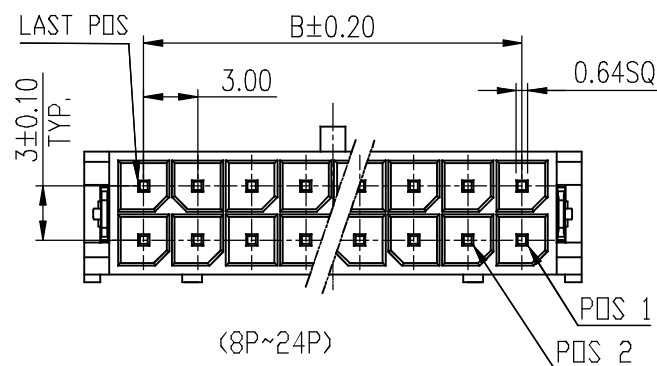
5.PACKING MUST BE PER Amphenol PACKING SPECIFICATION

6.TO ENSURE CURRENT RATING CAPABILITY, PLEASE ADOPT TOTAL SOLUTION.

(G88MPH CABLE HOUSING SERIES WITH G88MPC CABLE TERMINAL SERIES)



(W/O BOARDLOCK)



(W/BOARDLOCK)

POS	A	B	C	D
02	6.60		6.00	4.3
04	9.60	3.00	9.00	7.3
06	12.60	6.00	12.00	10.3
08	15.60	9.00	15.00	13.3
10	18.60	12.00	18.00	16.3
12	21.60	15.00	21.00	19.3
14	24.60	18.00	24.00	22.3
16	27.60	21.00	27.00	25.3
18	30.60	24.00	30.00	28.3
20	33.60	27.00	33.00	31.3
22	36.60	30.00	36.00	34.3
24	39.60	33.00	39.00	37.3

PART NO. G88MPXX1X2XXEU

No. OF CIRCUIT

BOARD MOUNT OPTION

C: W/BOARDLOCK

D: W/O BOARDLOCK

INSULATOR

BLANK: LCP (BLACK)

1: LCP (NATURAL)

CONTACT FINISH

0: MATTE TIN (OVERALL)

UNDER PLATING NICKEL 50 μ" THICKNESS MIN

1: FLASH GOLD (OVERALL)

2: 15 u" GOLD

3: 30 u" GOLD

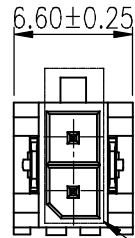
TOLERANCE		APPROVALS		DATE		TITLE			Amphenol [®]						
X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 ANGULAR ±1° UNLESS OTHERWISE SPECIFIED		DRAWN	Debby Hung	02/10/2015		G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK			Amphenol Corporation Amphenol Taiwan Corporation						
		CHECKED	Roger Tsai	02/10/2015											
		APPROVED	Arron Lin	02/10/2015											
DWG TYPE		CUST DWG		PROJECT CODE		PHD			UNIT	mm	SIZE	A3	PART No.	G88MPXX1X2XXEU	
									SCALE	NA	SHEET	1 OF 4	DWG No.	G88MPXX1X2XXEU	
													REV.	BX1	

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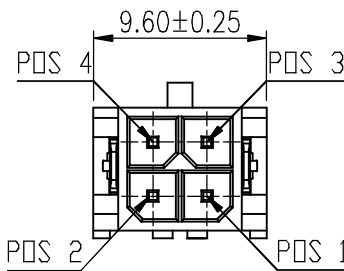
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REVISIONS				
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BX1	EDSR#5399	ADD W/O BOARDLOCK OPTION	02/10/2015	Arron Lin

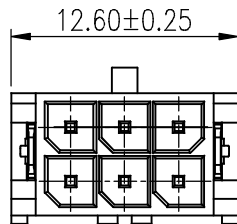
FOR REFERENCE ONLY



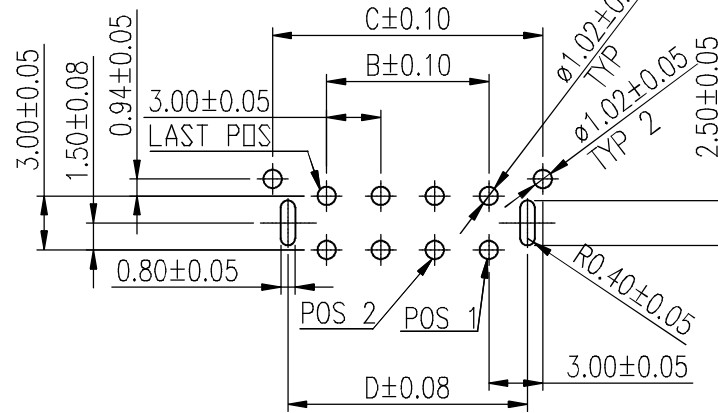
(2X1POS)



(2X2POS)

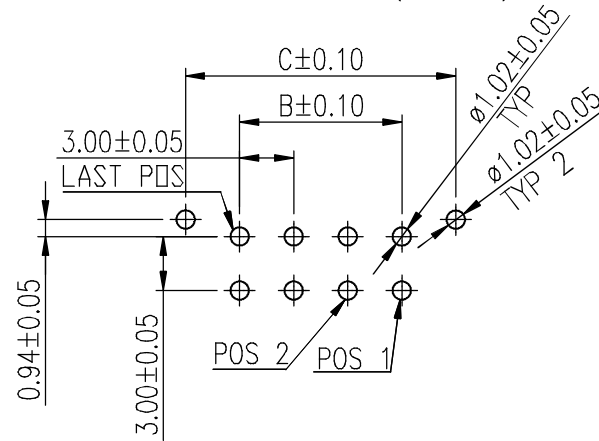


(2X3POS)



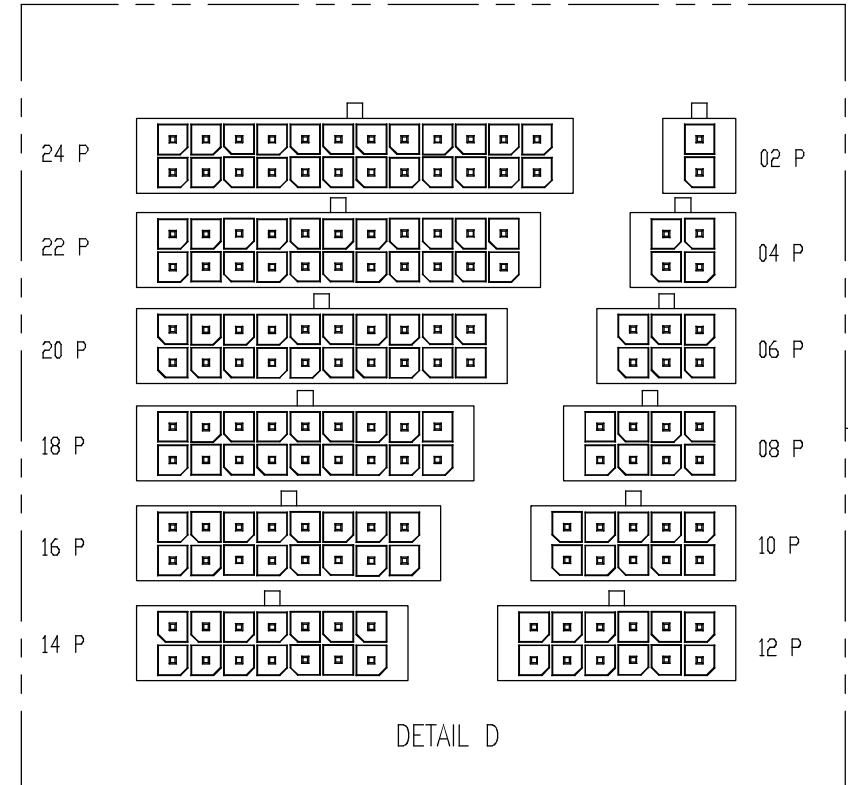
02~24P (W/BOARDLOCK)

RECOMMENDED PCB LAYOUT (T=1.60mm)



02~24P (W/O BOARDLOCK)

RECOMMENDED PCB LAYOUT (T=1.60mm)



DETAIL D

TOLERANCE		APPROVALS		DATE		TITLE			Amphenol [®]						
X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 ANGULAR ±1° UNLESS OTHERWISE SPECIFIED		DRAWN	Debby Hung	02/10/2015		G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK			Amphenol Corporation Amphenol Taiwan Corporation						
		CHECKED	Roger Tsai	02/10/2015											
		APPROVED	Arron Lin	02/10/2015											
		DWG TYPE	CUST DWG	PROJECT CODE	PHD									UNIT	mm
						SCALE		NA	SHEET	2 OF 4		DWG No.	G88MPXX1X2XXEU	REV.	BX1

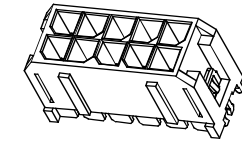
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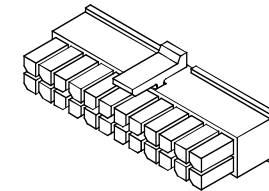
FOR REFERENCE ONLY

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-14098	RELEASE FOR RoHS	06/14/2014	Arron Lin
BX1	EDSR#5399	ADD W/O BOARDLOCK OPTION	02/10/2015	Arron Lin

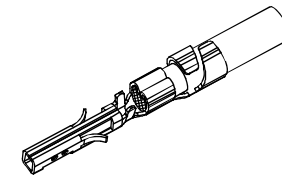
POS.	BOARD-MOUNT P/N	CABLE HOUSING P/N	CABLE TERMINAL P/N	AWG NO.	PLATING OPTIONS
02	G88MP021X2XXEU	G88MPH0222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
04	G88MP041X2XXEU	G88MPH0422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
06	G88MP061X2XXEU	G88MPH0622CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
08	G88MP081X2XXEU	G88MPH0822CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
10	G88MP101X2XXEU	G88MPH1022CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
12	G88MP121X2XXEU	G88MPH1222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
14	G88MP141X2XXEU	G88MPH1422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
16	G88MP161X2XXEU	G88MPH1622CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
18	G88MP181X2XXEU	G88MPH1822CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
20	G88MP201X2XXEU	G88MPH2022CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
22	G88MP221X2XXEU	G88MPH2222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
24	G88MP241X2XXEU	G88MPH2422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD



AMPHENOL BOARD-MOUNT



AMPHENOL CABLE HOUSING



AMPHENOL CABLE TERMINAL

NOTE:
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ADOPT TOTAL SOLUTION.
(G88MPH CABLE HOUSING SERIES WITH G88MPC
CABLE TERMINAL SERIES)

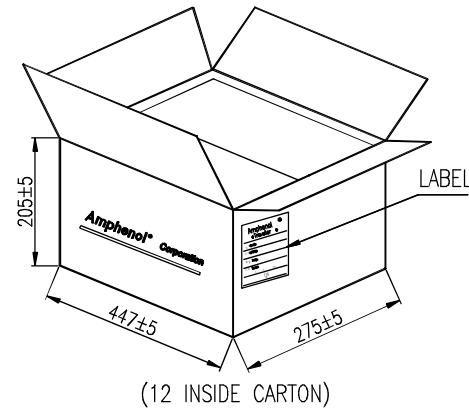
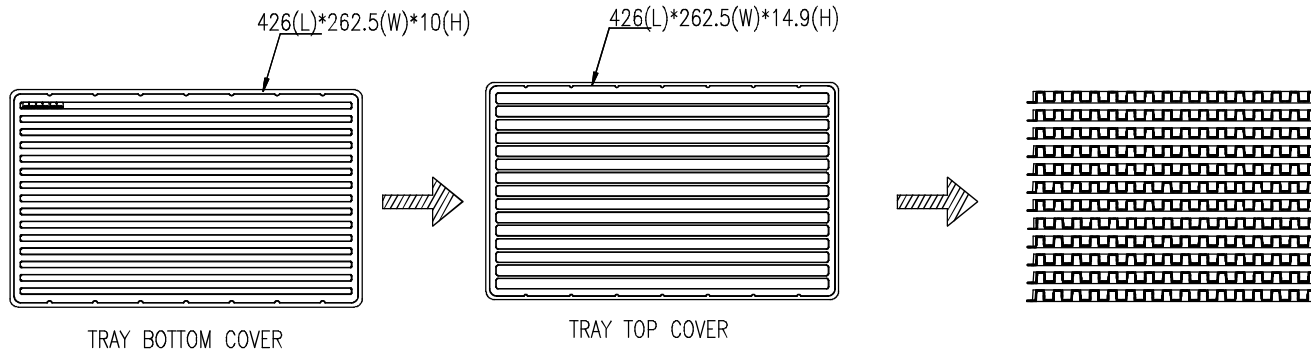
TOLERANCE		APPROVALS		DATE	TITLE			Amphenol [®]			
X. X.X X.XX X.XXX	±0.30 ±0.20 ±0.10	DRAWN	Debby Hung	02/10/2015	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK			Amphenol Corporation Amphenol Taiwan Corporation			
		CHECKED	Roger Tsai	02/10/2015							
		APPROVED	Arron Lin	02/10/2015							
ANGULAR ±1°						UNIT mm	SIZE A3	PART No. G88MPXX1X2XXEU			
UNLESS OTHERWISE SPECIFIED		DWG TYPE CUST DWG		PROJECT CODE PHD			SCALE NA	SHEET 3 OF 4	DWG No. G88MPXX1X2XXEU		REV BX1

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BX1	EDSR#5399	ADD W/O BOARDLOCK OPTION	02/10/2015	Arron Lin



POS	PCS/TRAY	PCS/CARTON
2	900	10800
4	615	7380
6	465	5580
8	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

NOTE:

1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
3. THICKNESS : 0.80 ± 0.05 mm.

TOLERANCE		APPROVALS		DATE	TITLE				Amphenol [®]				
X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10		DRAWN Debby Hung		02/10/2015	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK				Amphenol Corporation Amphenol Taiwan Corporation				
		CHECKED Roger Tsai		02/10/2015									
		APPROVED Arron Lin		02/10/2015									
ANGULAR ±1°						UNIT mm	SIZE A3	PART No. G88MPXX1X2XXEU					
UNLESS OTHERWISE SPECIFIED		DWG TYPE CUST DWG		PROJECT CODE PHD		SCALE NA	SHEET 4 OF 4	DWG No. G88MPXX1X2XXEU		REV. BX1			